CLAIMS

1. A curable resin composition comprising components (A) to (E) below and having a viscosity at 25°C of 10 Pa·s or less:

the component (A): a compound having two or more epoxy groups;

the component (B): silica treated with phenylaminosilane;

the component (C): a compound curing the component (A);

the component (D): a reactive diluent; and

the component (E): a thiol curing agent having two or more SH groups,

wherein the curable resin composition does not comprise a solvent.

2. The curable resin composition according to claim 1, wherein the component (A) is a compound having a bisphenol skeleton.

3. The curable resin composition according to claim 1 or 2, wherein the component (C) is an amine adduct latent curing agent.

4. The curable resin composition according to any one of claims 1 to 3, wherein a softening point or melting point of the component (C) is 150°C or lower.

5. The curable resin composition according to any one of claims 1 to 4, wherein the reactive diluent is an epoxy compound having an aromatic ring.

6. The curable resin composition according to any one of claims 1 to 5, wherein the thiol curing agent is a thiol curing agent containing no ester bond.

7. The curable resin composition according to any one of claims 1 to 6, being used for an adherend containing nickel.

8. A cured product of the curable resin composition according to any one of claims 1 to 7.